

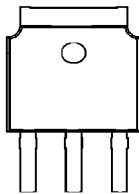
# TM100N03YS

# N-Channel Enhancement Mosfet

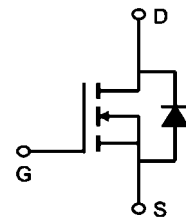
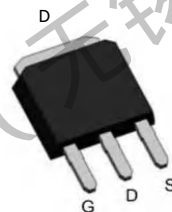
<p><b>General Description</b></p> <ul style="list-style-type: none"> <li>• Low <math>R_{DS(ON)}</math></li> <li>• RoHS and Halogen-Free Compliant</li> </ul> <p><b>Applications</b></p> <ul style="list-style-type: none"> <li>• Load switch</li> <li>• PWM</li> </ul>	<p><b>General Features</b></p> <p><math>V_{DS} = 30V</math> <math>I_D = 100A</math></p> <p><math>R_{DS(ON)} = 3.5m\Omega (typ) @ V_{GS} = 10V</math></p> <p>100% UIS Tested 100% <math>R_g</math> Tested</p>
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YS:TO-251S-3L



Marking: 100N03



**Absolute Maximum Ratings ( $T_C = 25^\circ C$  unless otherwise noted)**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	100	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	60	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	250	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>3</sup>	3.6	W
$P_D @ T_C = 25^\circ C$	Total Power Dissipation <sup>3</sup>	52	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup>	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction Case <sup>1</sup>	---	6.6	$^\circ C/W$



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## Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250μA	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V	-	-	1	μA
		T <sub>J</sub> =85°C	-	-	30	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250μA	0.9	1.2	1.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	3.5	5.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>DS</sub> =15A	-	5.5	6.8	
<b>Body Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage	I <sub>SD</sub> =40A, V <sub>GS</sub> =0V	-	0.7	1.3	V
<b>Dynamic Characteristics<sup>e</sup></b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =10V, Frequency=1.0MHz	-	1356	-	pF
C <sub>oss</sub>	Output Capacitance		-	55	-	
C <sub>rss</sub>	Reverse transfer capacitance		-	45	-	
t <sub>d(ON)</sub>	Turn-on delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V R <sub>G</sub> =1.8Ω, I <sub>D</sub> =20A, R <sub>L</sub> =30Ω	-	8	-	nS
t <sub>r</sub>	Turn-on rise Time		-	9	-	
t <sub>d(OFF)</sub>	Turn-off delay Time		-	32	-	
t <sub>f</sub>	Turn-off rise Time		-	6	-	
<b>Gate Charge Characteristics<sup>e</sup></b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	23	-	
Q <sub>gs</sub>	Gate-Source Charge		-	5	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	3	-	

Note: 1. Pulse test: pulse width<=300uS, duty cycle<=2%

2.Static parameters are based on package level with recommended wire bonding



### Typical Performance Characteristics

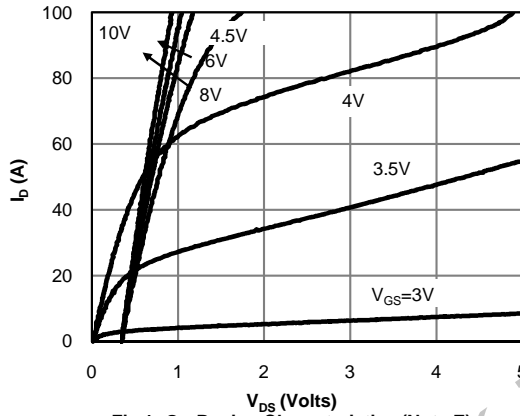


Fig 1: On-Region Characteristics (Note E)

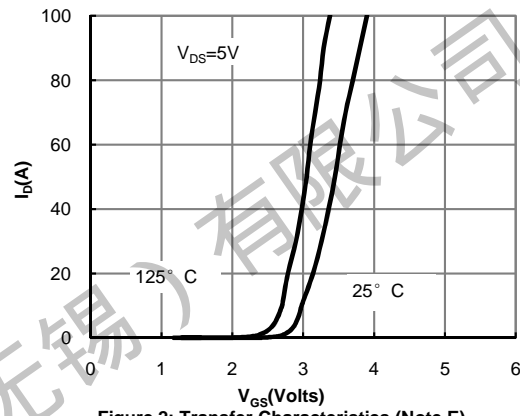


Figure 2: Transfer Characteristics (Note E)

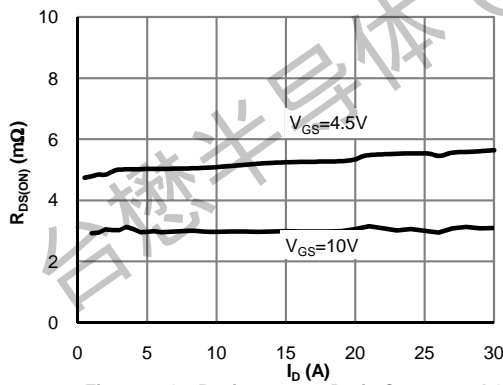


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

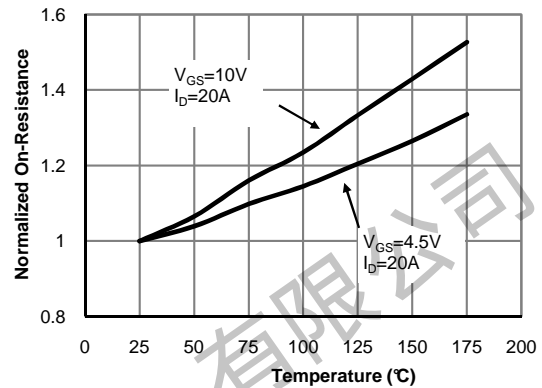


Figure 4: On-Resistance vs. Junction Temperature (Note E)

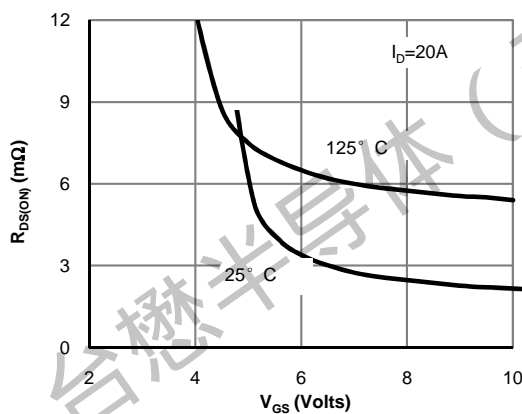


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

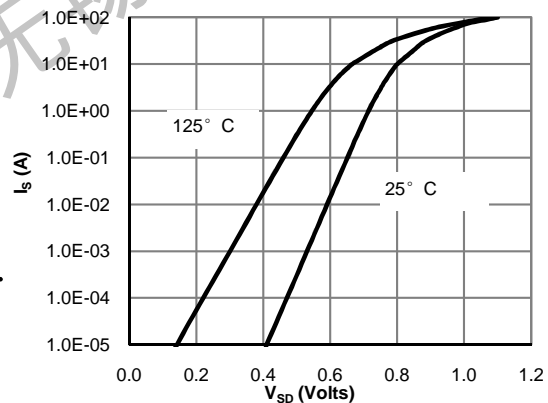


Figure 6: Body-Diode Characteristics (Note E)



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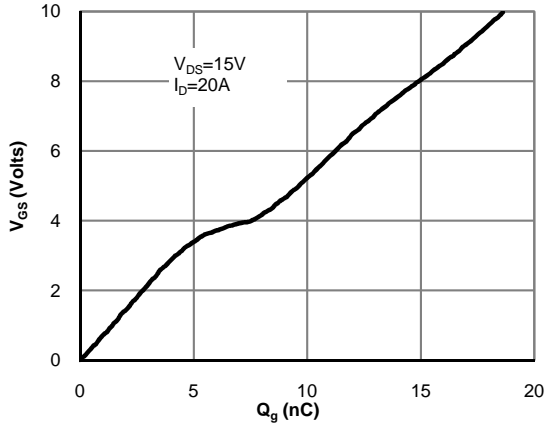


Figure 7: Gate-Charge Characteristics

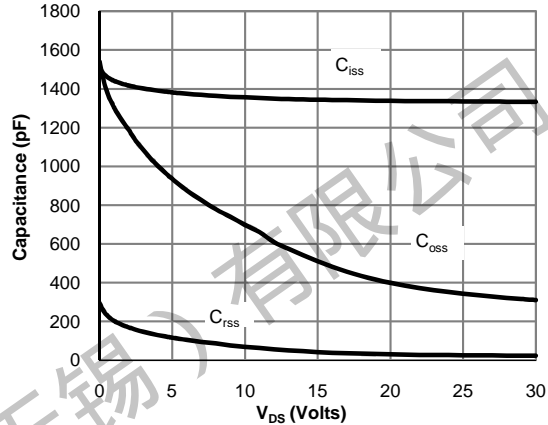


Figure 8: Capacitance Characteristics

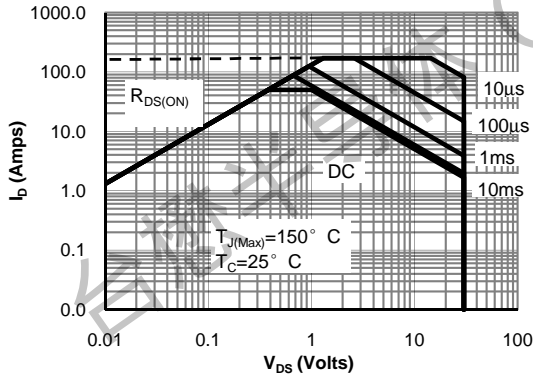


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

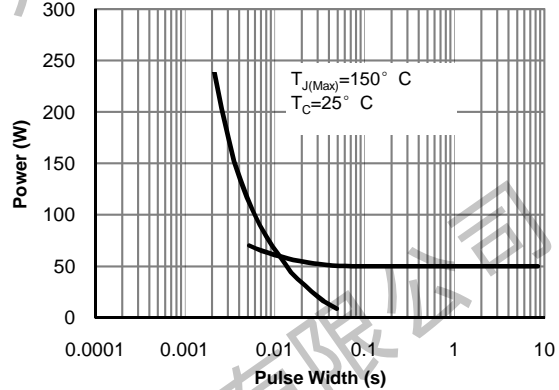


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

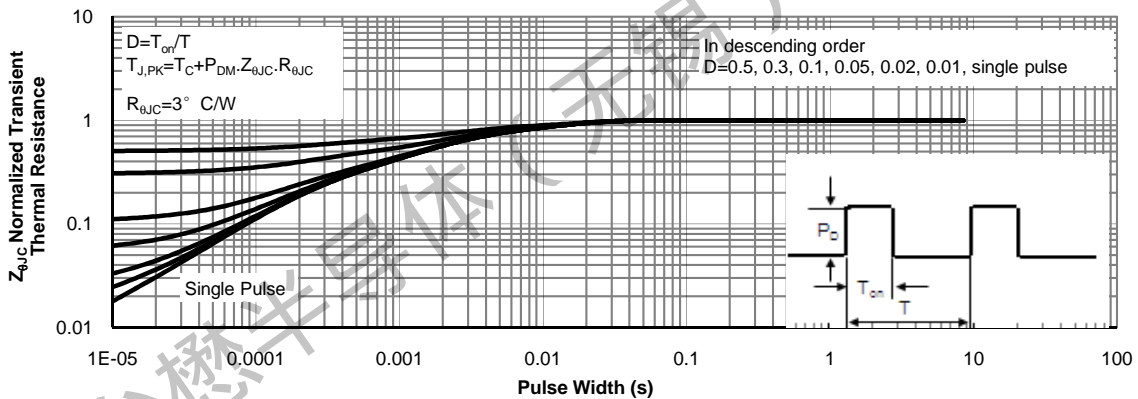


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

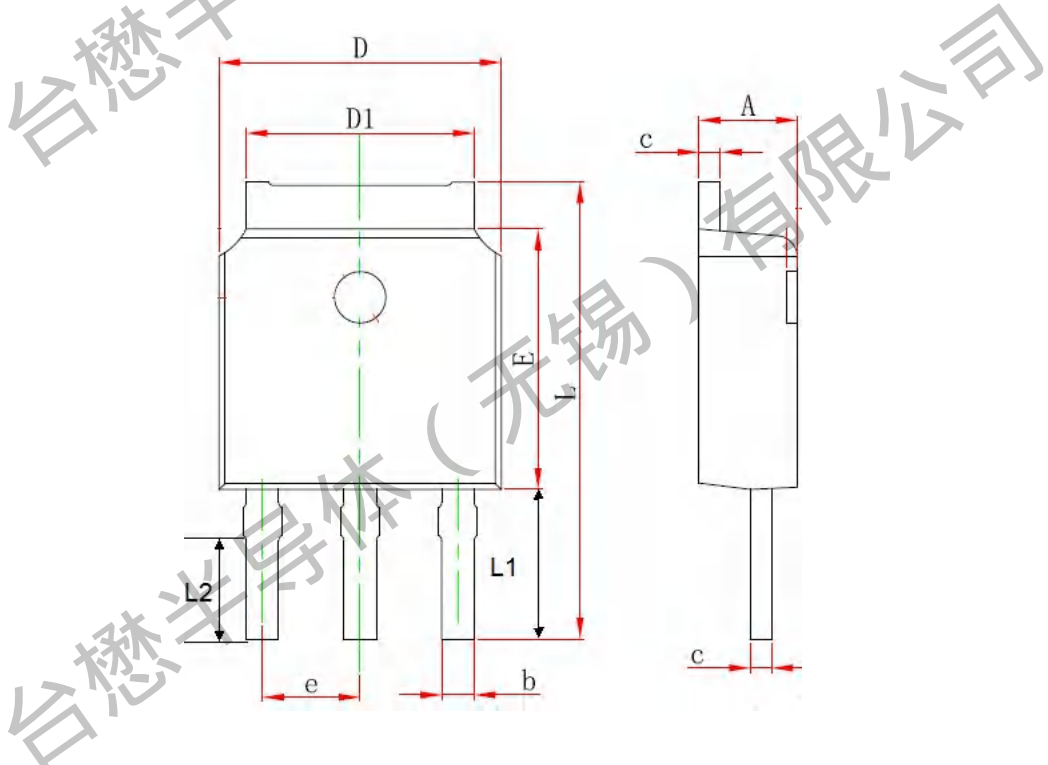
TM100N03YS

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Package Mechanical Data:TO-251S-3L

UNIT: mm

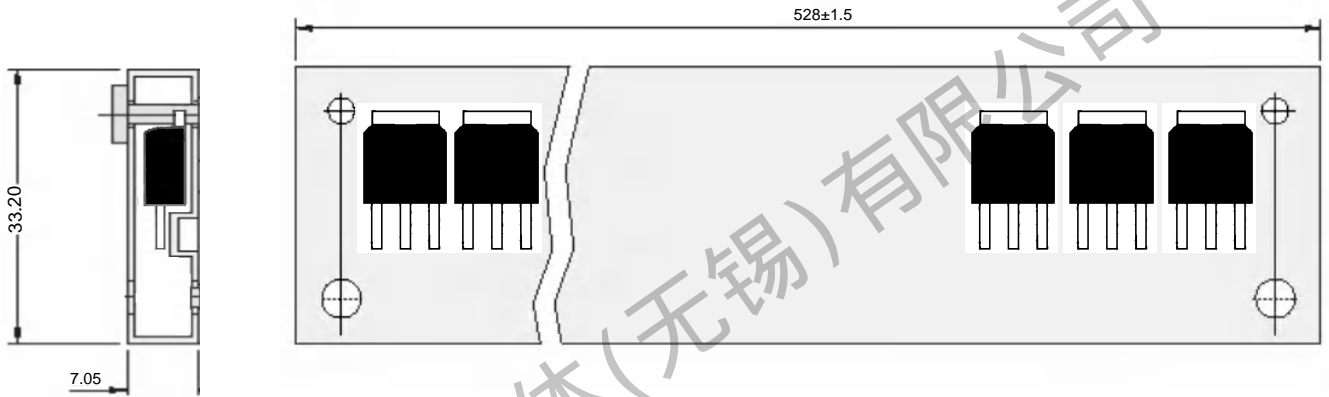
SYMBOL	min	nom	max
A	2.20		2.40
b	0.50		0.85
C	0.45	0.50	0.60
D	6.50		6.70
D1	5.10		5.50
E	5.9		6.20
e	2.18	2.29	2.38
L	11.00		12.40
L1	3.9		4.2
L2	2.7		3.0





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All Dimensions are in mm

**1.TO-251S-3L Packaging**

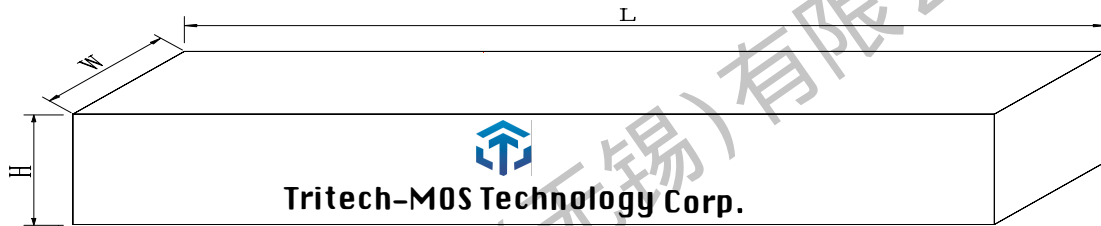
Package	Packing Form	Quantity		
		Tube	Inner Box	Outbox
TO-251S-3L	Tube Tape	80 Or 75	5 Or 6	1



**TM100N03YS**

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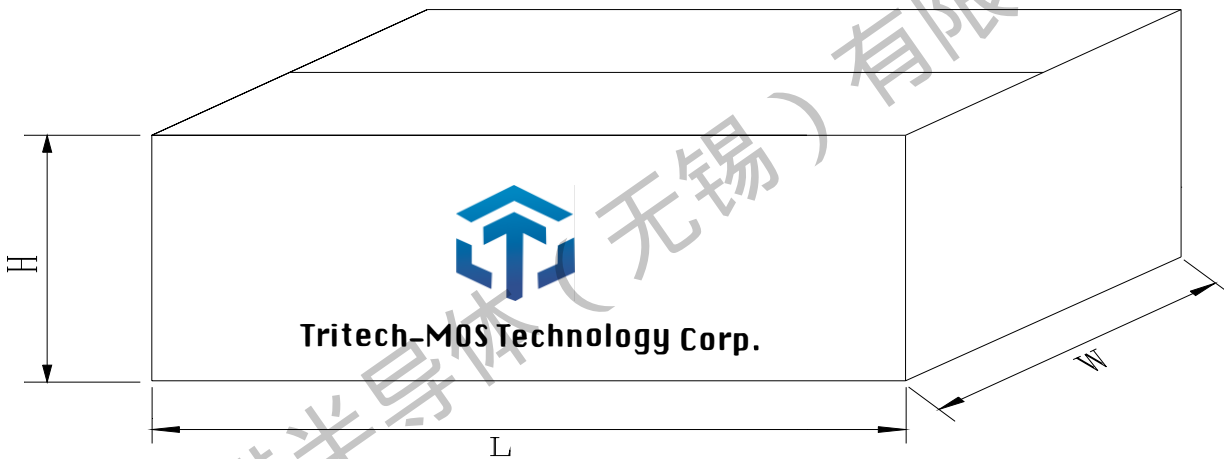
**Inner Box**



**Dimension : 580 (L)×154(W) ×49(H) mm**

**Quantity : 80 × 50Ea = 4000pcs Or 75 × 56Ea = 4200pcs**

**Outer Box**



**Dimension : 595(L)×285(W) ×185(H) mm**

**Quantity : 4000 × 6Ea = 24000pcs Or 4200 × 5Ea = 21000pcs**



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Revision history:

Date	Rev	Description	Page
2023.07.21	23.07	Original	